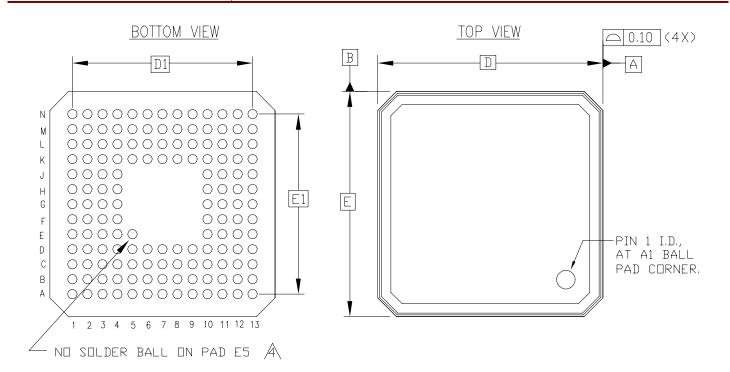
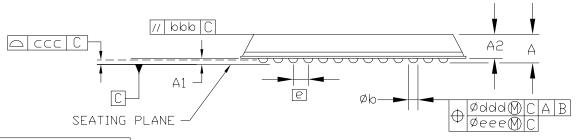
Chip Scale BGA (CS144) Package





S Y M B	MILLIMETERS		
L	MIN.	N□M.	MAX.
Α	*	*	1.20
A 1	0.20	*	4
Α ₂	0.65	*	*
D/E	12.00 BSC		
D ₁ /E ₁	9.60 BSC		
6	0.80 BSC		
Øb	0.40	0.45	0.50
bbb	*	*	0.20
CCC	4	14	0.12
ddd	4	14	0.15
666	*	*	0,08
М	13		

NOTES:

- 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
- 2. SYMBOL "M" IS THE PIN MATRIX SIZE.
- 3. CONFORMS TO JEDEC MO-216-BAG-2 (DEPOPULATED).
- A PAD 'E5' IS FOR PAD 'A1' CORNER INDICATION.

144-BALL CHIP SCALE BGA (CS144)

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